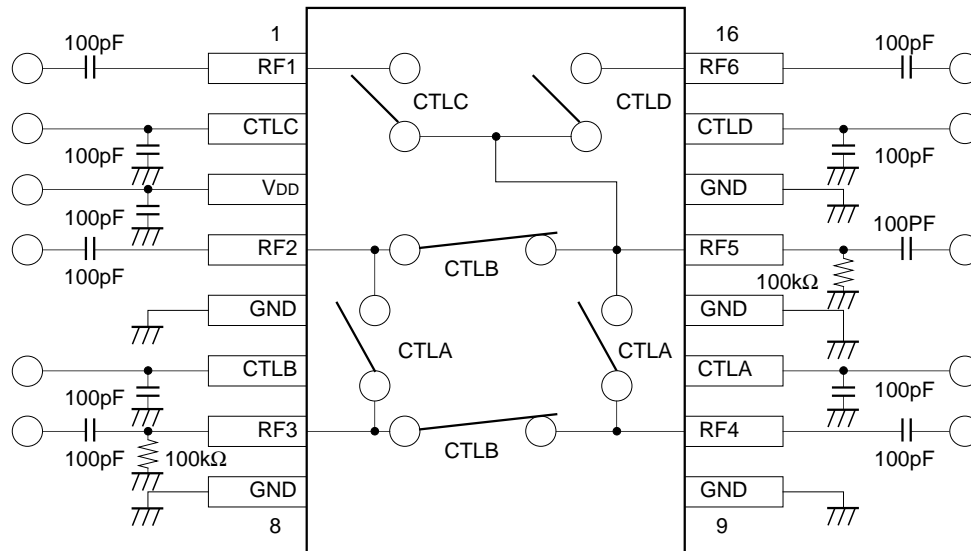


Pin Configuration and Recommended Circuit



Logic Table

ON-Port	CTLA	CTLB	CTLC	CTLD
RF3–RF2	H	L	H or L	H or L
RF3–RF4	L	H	H or L	H or L
RF5–RF2	L	H	L	L
RF5–RF4	H	L	L	L
RF5–RF6	L	L	L	H
RF5–RF1	L	L	H	L

Recommended Operating Conditions

Item	Symbol	Min.	Typ.	Max.
Control Voltage (high)	Vctl (H)			6
Control Voltage (low)	Vctl (L)	-6		
Difference of Control Voltage	Vctl (H)–Vctl (L)			6
Supply voltage	VDD	Vctl (H)–0.6	Vctl (H)–0.5	Vctl (H)–0.4

Electrical Characteristics

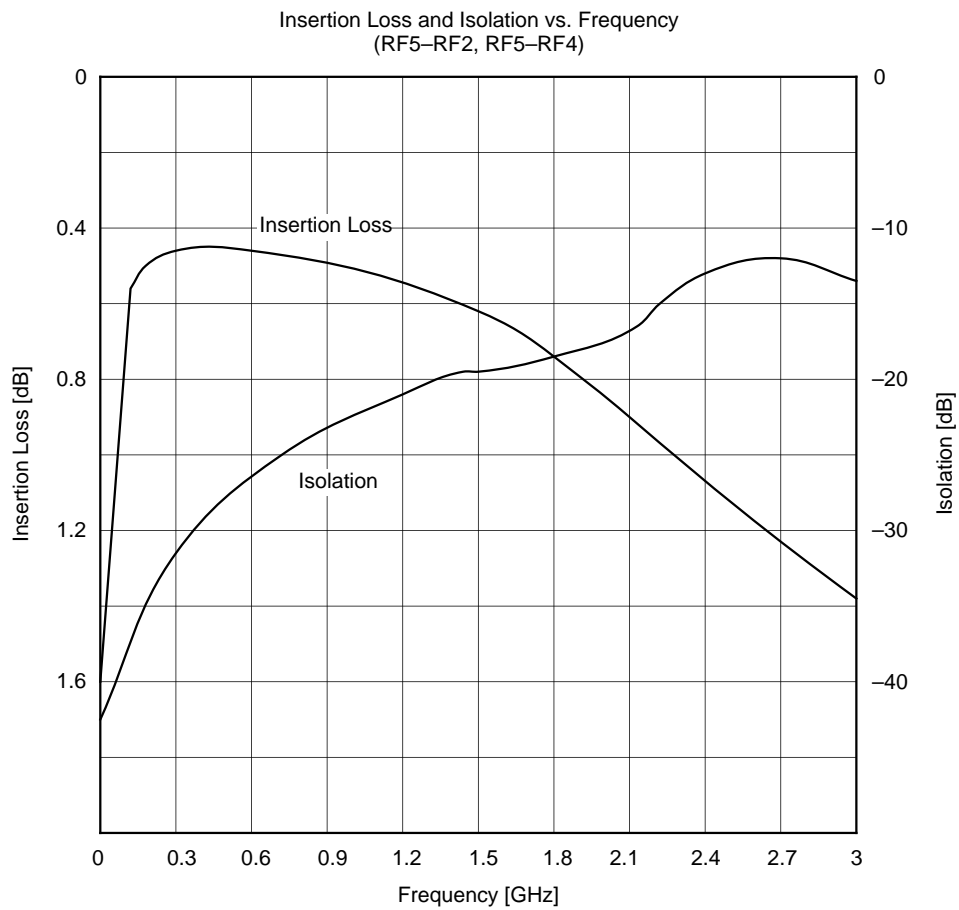
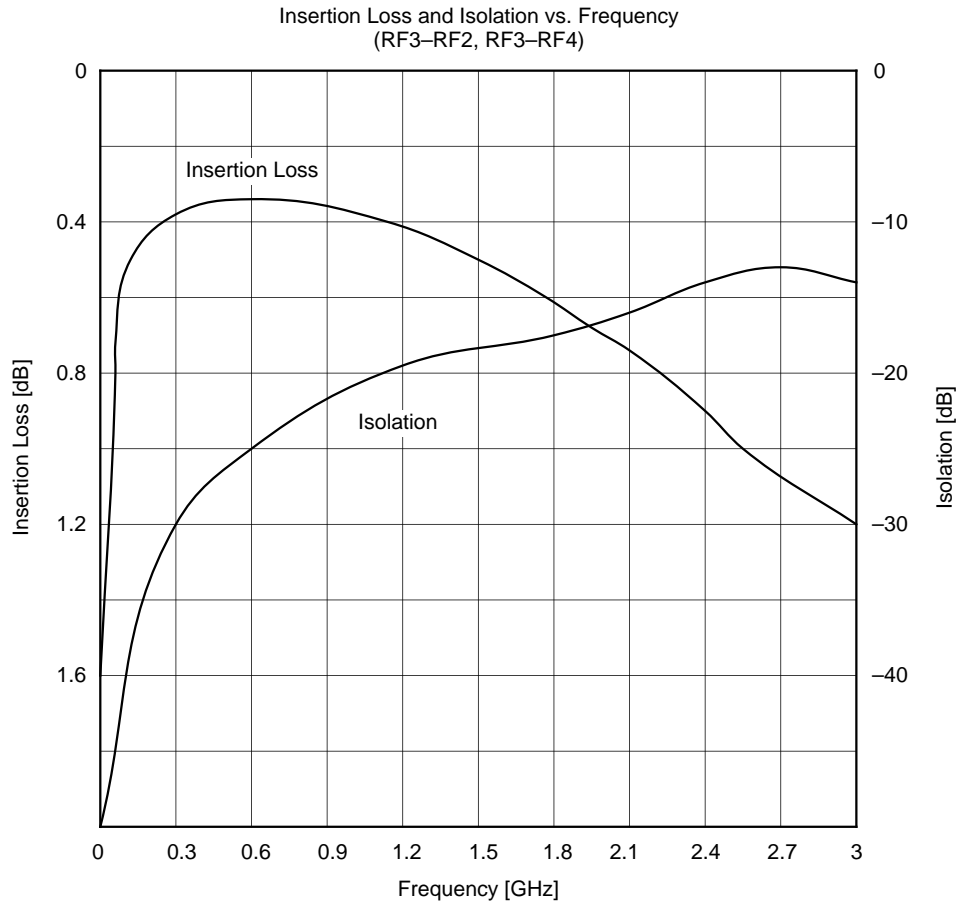
(Ta=25 °C)

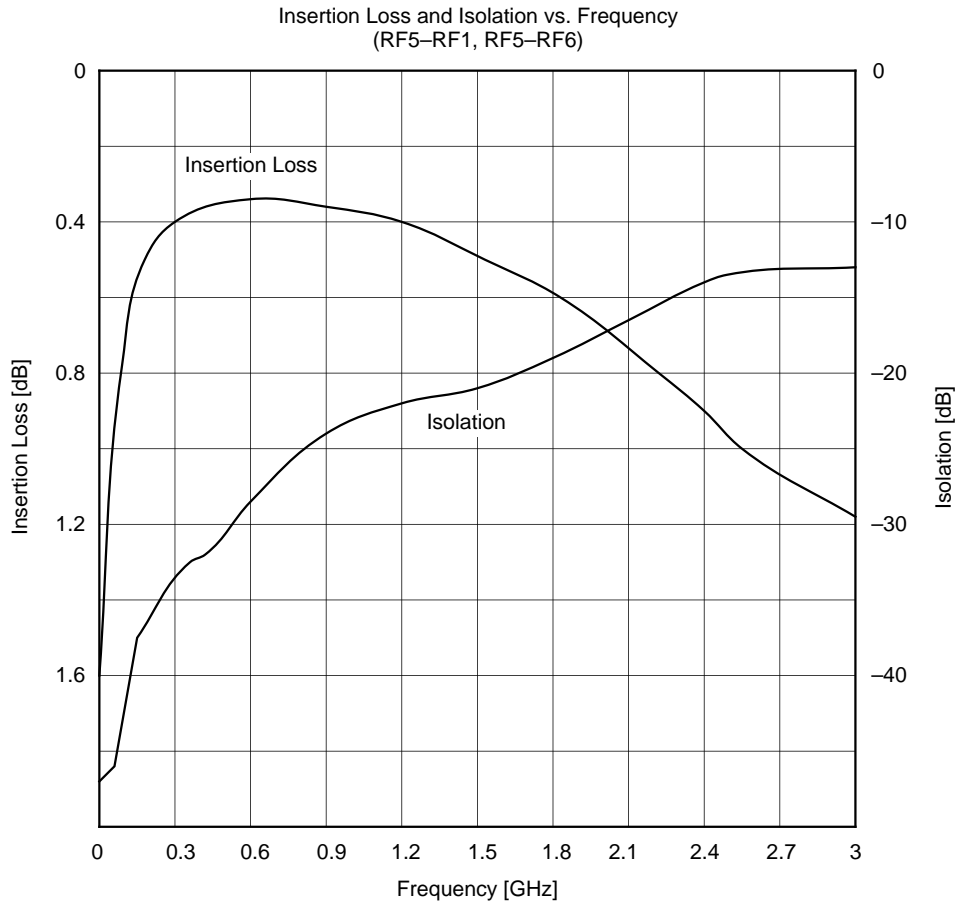
	Symbol	Signal Passes	Test Condition	Frequency	Min.	Typ.	Max.	Unit
Insertion Loss	IL.	RF3–RF2	*2	1 GHz		0.4	0.65	dB
		RF3–RF4	Pin=30 dBm	1.5 GHz		0.5	0.8	
				2 GHz		0.7	1.0	
		RF5–RF2	*2	1 GHz		0.5	0.8	
		RF5–RF4	Pin=20 dBm	1.5 GHz		0.65	0.95	
				2 GHz		0.9	1.2	
		RF5–RF4	*2	1 GHz		0.6	0.9	
			Pin=20 dBm	1.5 GHz		0.75	1.05	
				2 GHz		1.2	1.5	
		RF5–RF1	*2	1 GHz		0.4	0.7	
		RF5–RF6	Pin=20 dBm	1.5 GHz		0.5	0.8	
				2 GHz		0.7	1.0	
Isolation	ISO.	RF3–RF2	*2	1 GHz	18	21		dB
		RF3–RF4	Pin=30 dBm	1.5 GHz	15	18		
		RF5–RF2		2 GHz	12	15		
		RF5–RF4						
		RF5–RF1	*2	1 GHz	21	24		
		RF5–RF6	Pin=20 dBm	1.5 GHz	17	20		
				2 GHz	15	18		
VSWR	VS.	RF3–RF2	*2	0.1 to 2 GHz		1.3	1.5	
		RF3–RF4	Pin=30 dBm					
		RF5–RF2	*2	0.1 to 2 GHz		1.3	1.5	
		RF5–RF4	Pin=20 dBm					
		RF5–RF1						
		RF5–RF6						
1 dB Compression Power	P1 dB	RF3–RF2	*3	1.5 GHz	30	32		dBm
		RF3–RF4	*2	1.5 GHz	33	35		
			*1	1.5 GHz	35	37		
		RF5–RF2	*3	1.5 GHz	22	24		
		RF5–RF4	*2	1.5 GHz	25	27		
		RF5–RF1	*1	1.5 GHz	27	29		
Switching Time	tsw			0.1 to 2 GHz			200	nsec
Control Current	Ictl							μA
			*2				100	
Supply Current	IDD							μA
			*2				100	

*1 : Vctl (H)=5 V, Vctl (L)=0 V, VDD=4.5 V

*3 : Vctl (H)=3 V, Vctl (L)=0 V, VDD=2.5 V

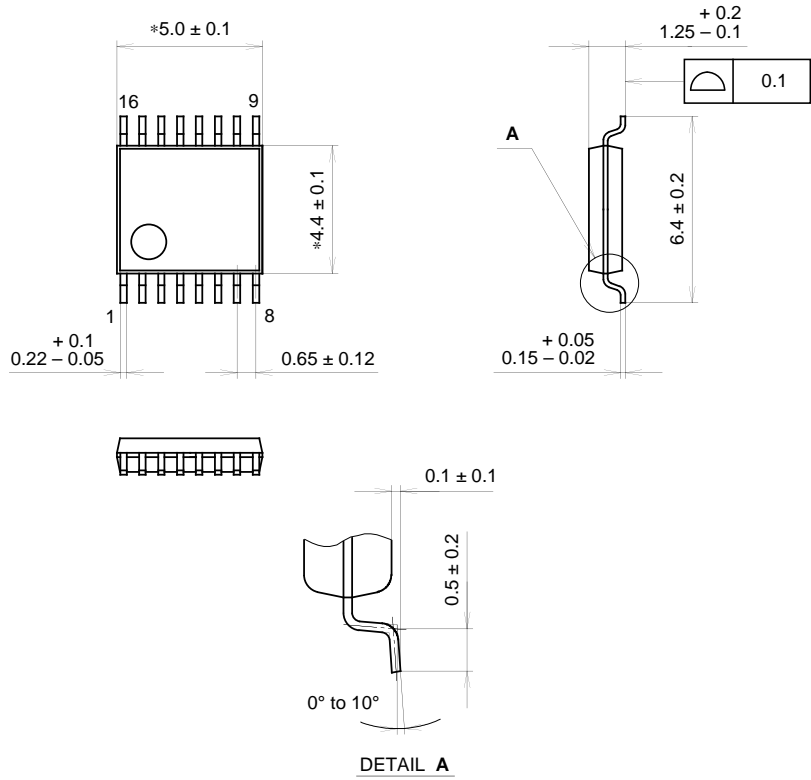
*2 : Vctl (H)=4 V, Vctl (L)=0 V, VDD=3.5 V





Package Outline Unit : mm

16PIN SSOP (PLASTIC)



NOTE: Dimension "*" does not include mold protrusion.

PACKAGE STRUCTURE

SONY CODE	SSOP-16P-L01
EIAJ CODE	SSOP016-P-0044
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER / PALLADIUM PLATING
LEAD MATERIAL	COPPER / 42 ALLOY
PACKAGE WEIGHT	0.1g